





Flat-Panel Display Systems With Mass-Transferred MicroLEDs And MicroICs

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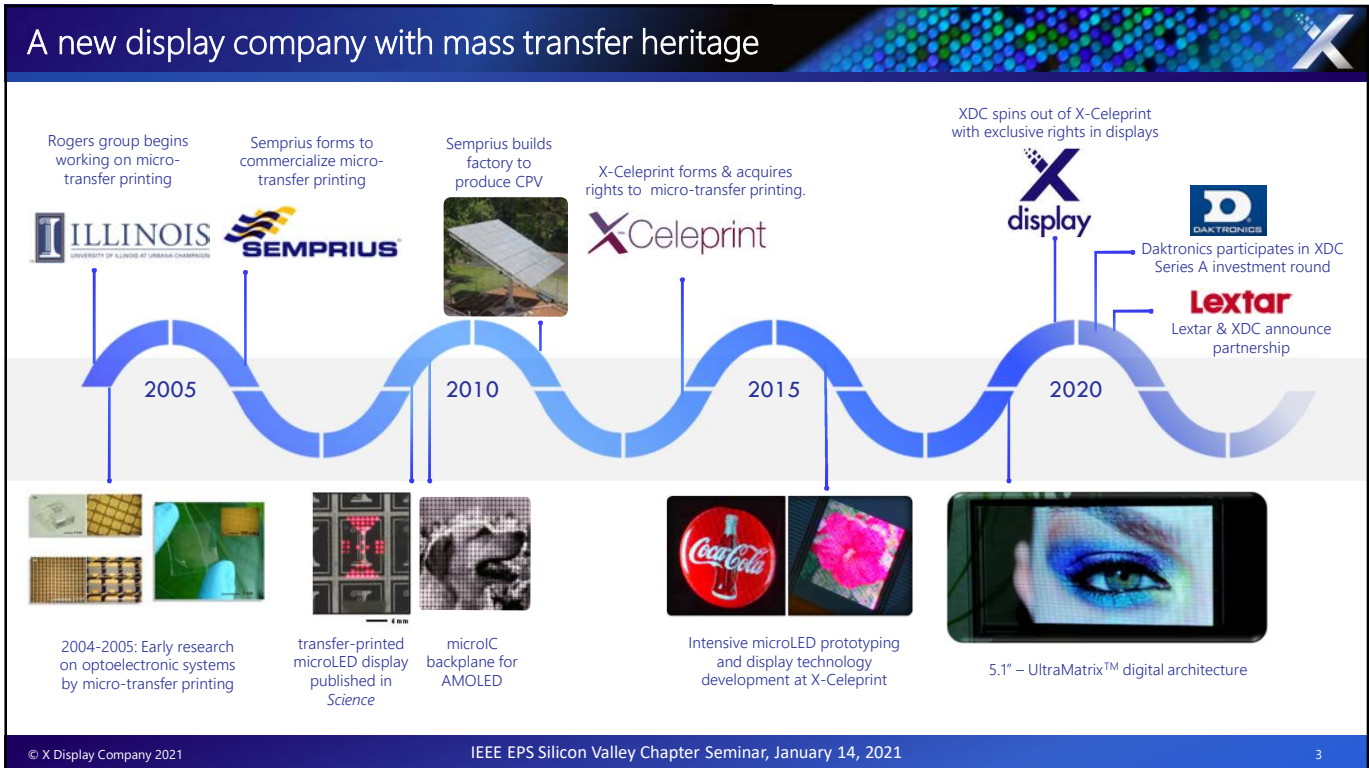
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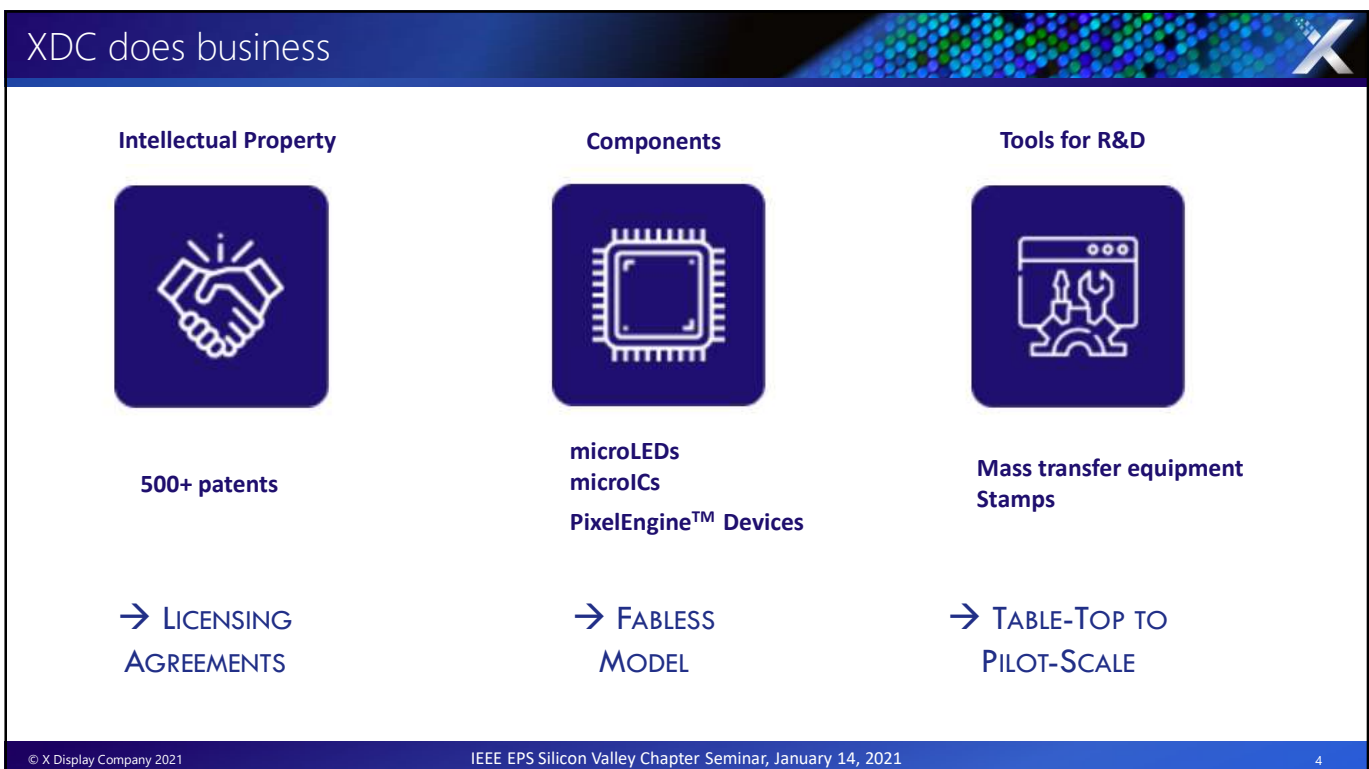
- Introducing XDC
- Elastomer stamp mass transfer
- Mass transfer for displays

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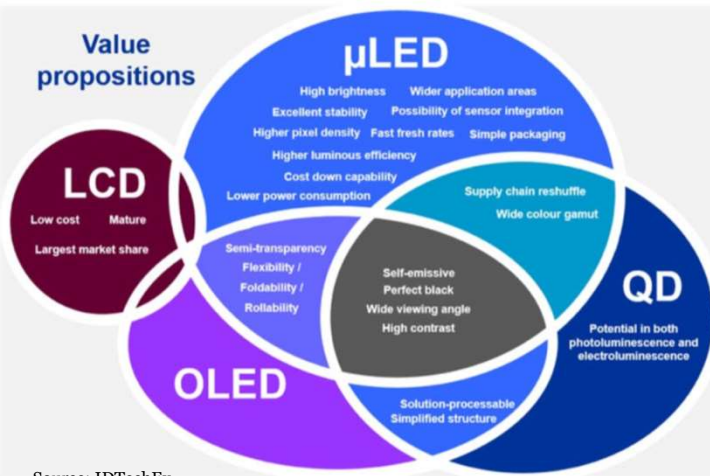


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## Better materials make better displays



COMPARISONS WITH LCD AND OLED

	LCD	OLED	microLEDs
Energy consumption	Medium	Medium	Very Low
Pixel density	Up to 1000 PPI (Current commercial: 500)	2500 PPI demonstrated (MicroDisplays)	Up to 5000 PPI
Brightness	< 2000 Cd/m <sup>2</sup>	<1000 Cd/m <sup>2</sup>	Up to 1E6 Cd/m <sup>2</sup>
Contrast	Low to medium	High	High
Lifetime	Good	Medium	Best
Environmental stability	Good	Medium (with appropriate encapsulation)	Best
Refresh Rates	Low (ms)	High (μs)	Very high (ns)
Viewing angles	Low	High	High
Flexibility	Low	High	Medium
Maturity	High	Medium	Low
Cost	Low	Medium	High

Yole Development 2017 "MicroLED Displays: Hype and Reality, Hopes and Challenges"

Mass transfer brings the best materials to displays

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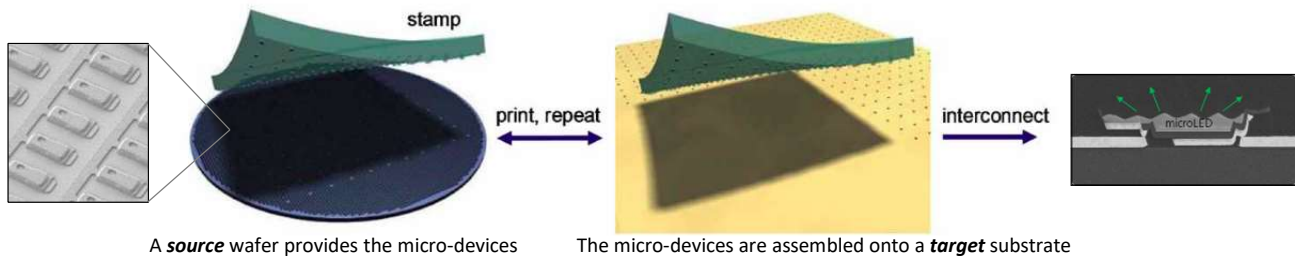
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## Micro-transfer printing: elastomer stamp mass transfer

1. Form undercut microdevices (LEDs, ICs, etc.), anchored at endpoints
2. Mass transfer to the target (display) substrate with a patterned elastomer stamp
3. Form interconnections to complete functional systems



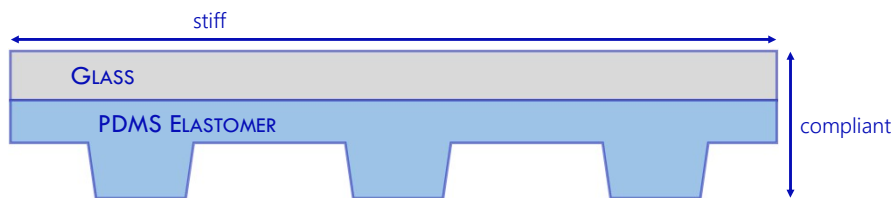
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## Elastomer stamp mass-transfer fundamentals

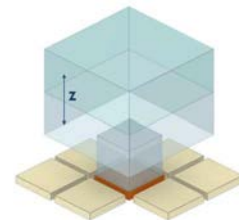


Elastomer stamp performs mass transfer by selectively retrieving an array of devices by van der Waals' adhesion and transferring the array to a display substrate (e.g. glass or plastic).

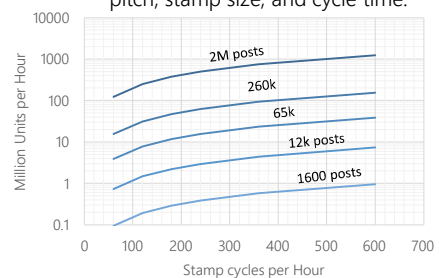
4 9s (99.99%) yield proven in R&D lab. Expect 6 9s or higher in production.

### STAMP CHARACTERISTICS:

- compliant in z-direction
  - short-range, rate-tunable adhesion
  - transparent
  - low-cost
  - mechanically tough
- Key enablers for yield and throughput



Throughput (UPH) determined by array pitch, stamp size, and cycle time.



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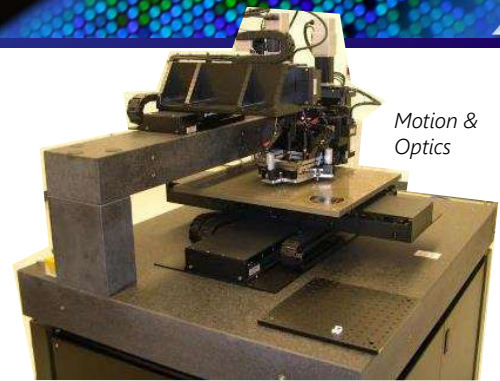
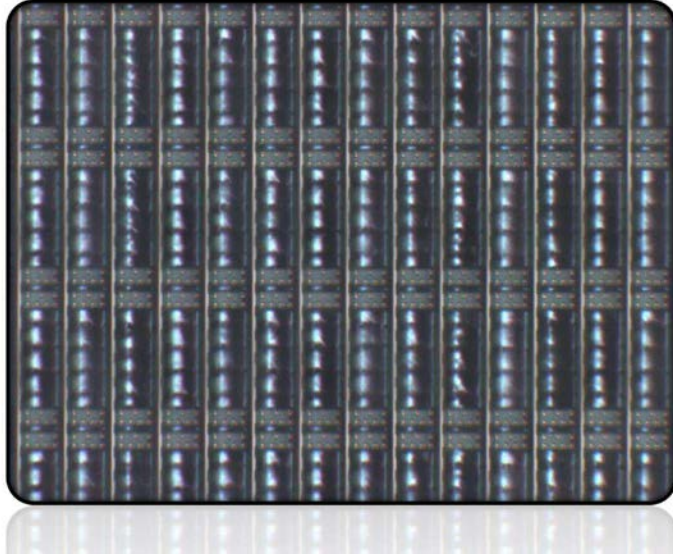
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## Mass-transfer in action → motion + optics

Looking through the stamp:  
Retrieve ICs with stamp, print to display, loop video.



This video shows 20 second cycle time.

Note orientational control (7 contact pads on IC).

Mechanical array alignment can define the rate of deterministic mass-transfer micro-assembly.

Transfer forces act only for a few seconds of the cycle (very fast).

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## XDC supplies mass transfer equipment



Transfer-printer designed to populate 300mm diameter wafers



Transfer-printer with automated substrate handling

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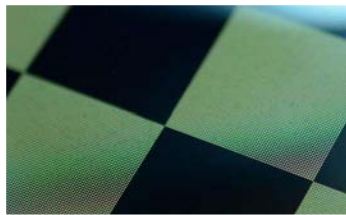
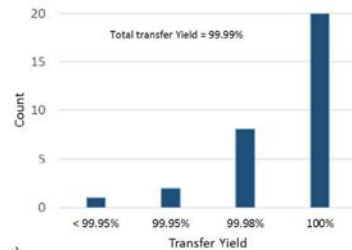
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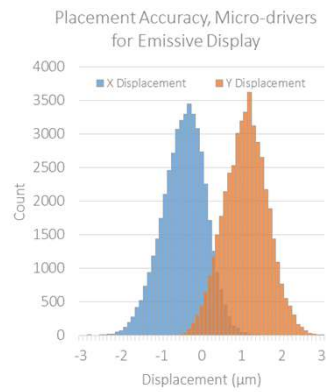
## Capability demonstrations

high transfer yields in R&D setting

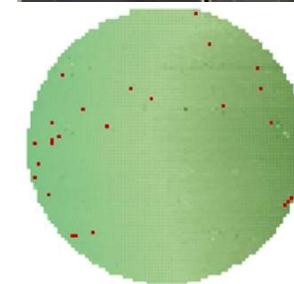
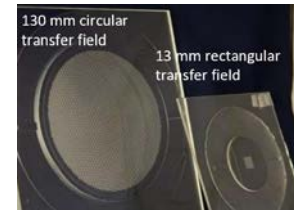


high accuracy placement

displacement at  $3\sigma$ :  $\pm 1.5 \mu\text{m}$



scalable transfer area



99.95% transfer yield

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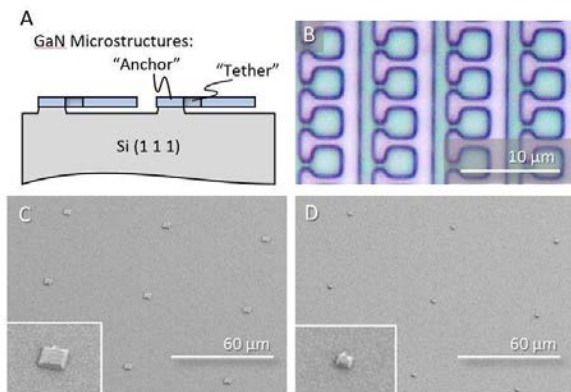
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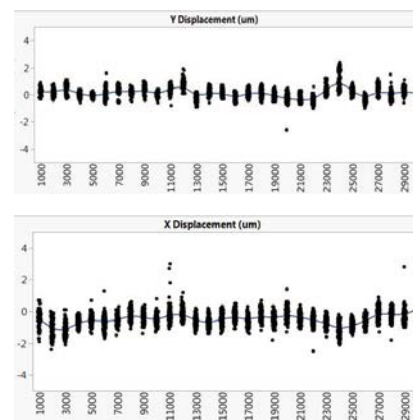
## Capability demonstrations

$3 \times 3 \mu\text{m}$  chips printed at  $60 \mu\text{m}$  pitch



stamp lifetime studies

> 30,000 transfers without performance degradation




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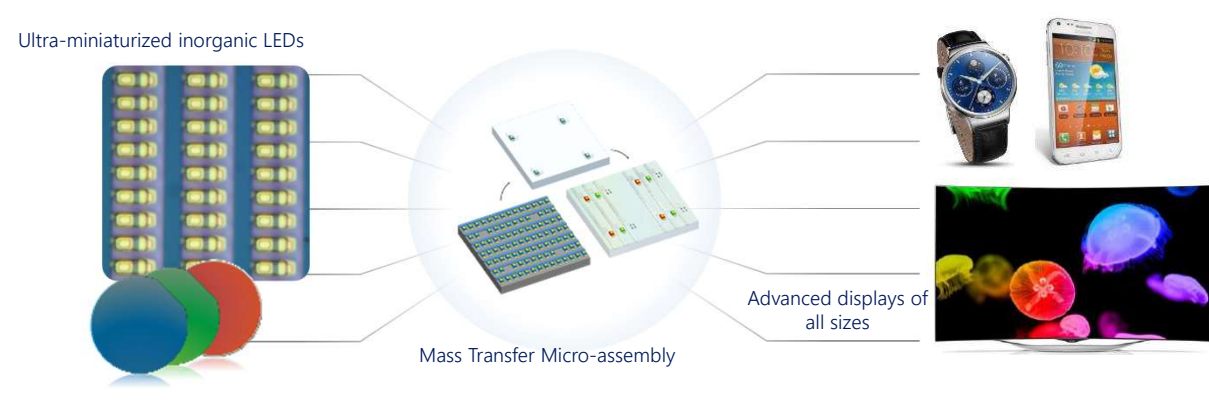
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## Better materials make better displays



Ultra-miniaturized inorganic LEDs

Mass Transfer Micro-assembly

Advanced displays of all sizes

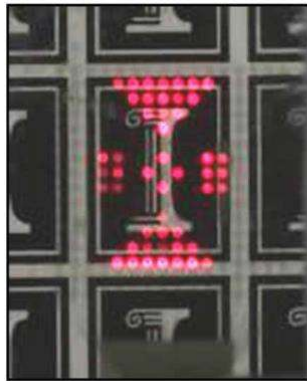
MicroLEDs for displays that...

...use less energy; have brightness suitable for the outdoors; are environmentally robust and long-lived; have high refresh rates; have wide viewing angles; have great contrast, etc...

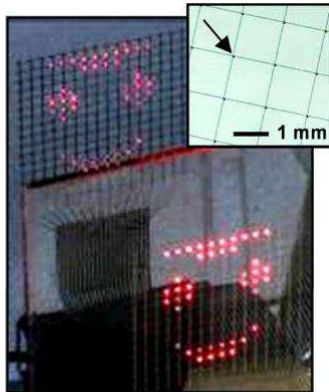
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## Transparent, bi-directional microLED display



*Science* 325, 977 (2009). — 5 mm



— 5 mm

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**Brighter idea for bendy displays**

The technology behind giant video billboards can now be made into flexible and even transparent displays.

These could be used to create brakelights that fit the curves of a car or medical diagnostics that envelop a patient like a blanket.

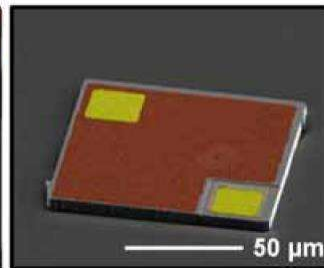
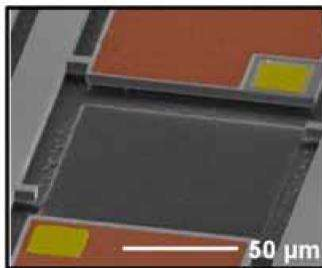
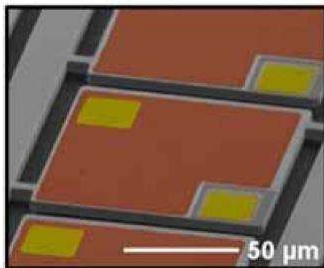
It has been made possible by a new technique, outlined in *Science*, for manufacturing so-called inorganic LEDs.

The new method allows these tiny light-emitting diodes (LEDs) to be attached to materials such as glass or rubber.

One of the researchers' prototypes wraps neatly around a thumb

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## Printable InGaN microLEDs and display

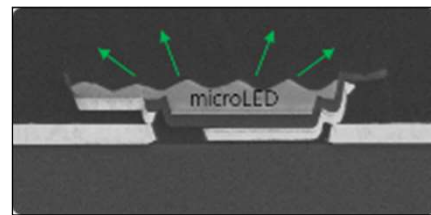
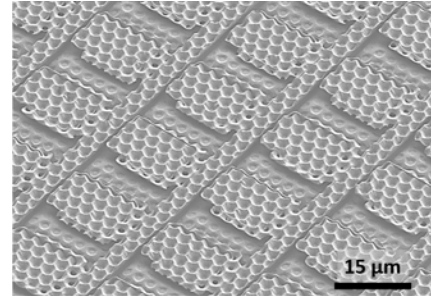
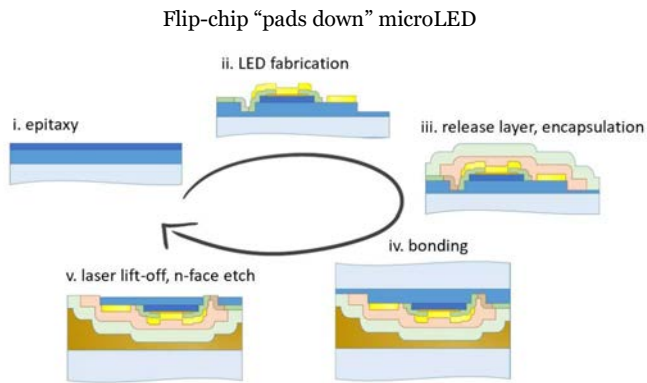


*PNAS* 108, 10072 (2011).

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## Print-ready 8 x 15 $\mu\text{m}^2$ flip-chip microLEDs



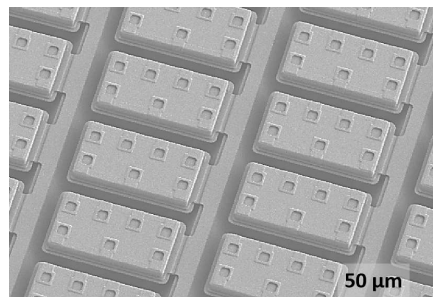
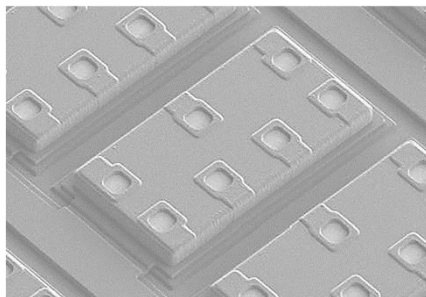
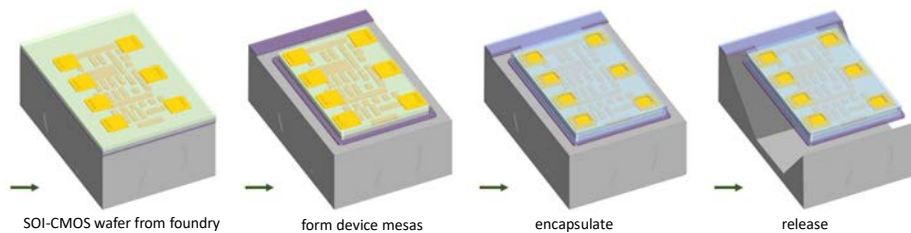
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## Print-ready microICs



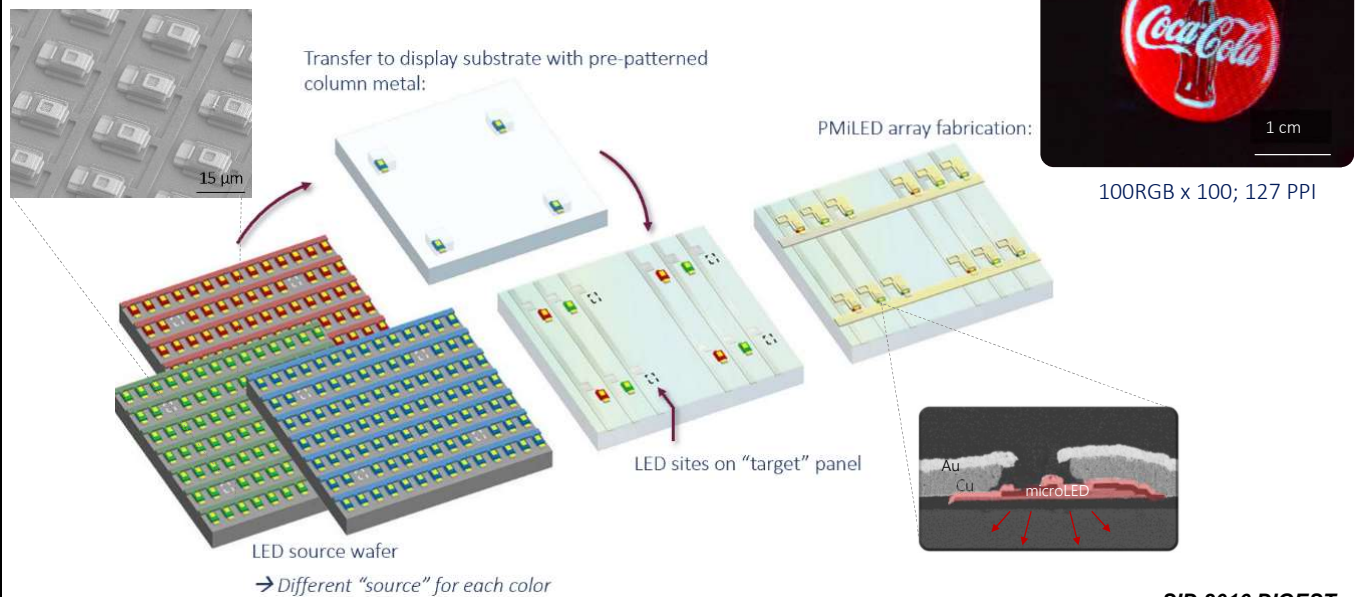
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## Passive matrix microLED displays by printing



SID 2016 DIGEST

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## Mass transfer brings more than microLED...

... it brings displays without limits

Photodiodes

Lasers

VCSELs

Hall Plates

Solar cells

Piezoelectric

GaN HEMTs

InP HBTs

Quantum Dots

Kim, Rak-Hwan, et al. "Waterproof AllInGaP optoelectronics on stretchable substrates with applications in biomedicine and robotics." *Nature materials* 9.11 (2010)

Justice, John, et al. "Wafer-scale integration of group III-V lasers on silicon using transfer printing of epitaxial layers." *Nature Photonics* 6.9 (2012)

Kang, Dongseok, et al. "Compliant, heterogeneously integrated GaAs micro-VCSELs towards wearable and implantable integrated optoelectronics platforms." *Advanced Optical Materials* 2.4 (2014)

Bower, Christopher A., et al. "Heterogeneous integration of microscale compound semiconductor devices by micro-transfer-printing." 2015 IEEE 65th ECTC, 2015.

Sheng, Xing, et al. "Printing-based assembly of quadruple-junction four-terminal microscale solar cells and their use in high-efficiency modules." *Nature materials* 13.6 (2014)

Dagdeviren, Canan, et al. "Conformal piezoelectric systems for clinical and experimental characterization of soft tissue biomechanics." *Nature materials* 14.7 (2015)

Lerner, Ralf, et al. "Flexible and Scalable Heterogeneous Integration of GaN HEMTs on Si-CMOS by Micro-Transfer-Printing." *physica status solidi (a)* 215.8 (2018)

Carter, Andrew D., et al. "Microtransfer-Printed InGaAs/InP HBTs Utilizing a Vertical Metal Sub-Collector Contact." 2019 Device Research Conference (DRC). IEEE, 2019.

Kim, Tae-Ho, et al. "Full-colour quantum dot displays fabricated by transfer printing." *Nature photonics* 5.3 (2011)

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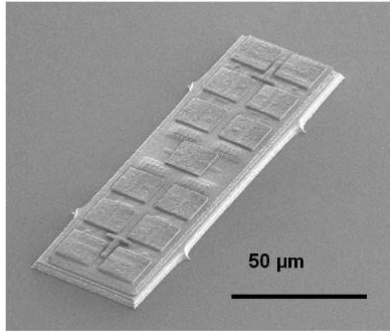
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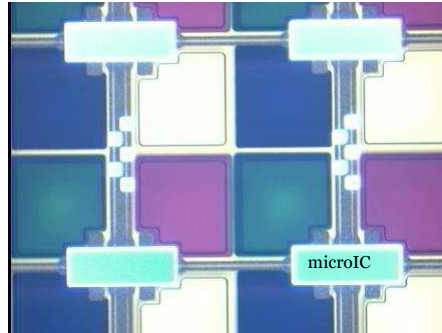
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## Mass transfer brings microICs to displays

Kodak and Semprius demonstrated AMOLED backplanes using mass transferred microICs in the late 2000s.



A transferred pixel driver microIC



Looking through the down-emitting full-color AMOLED.

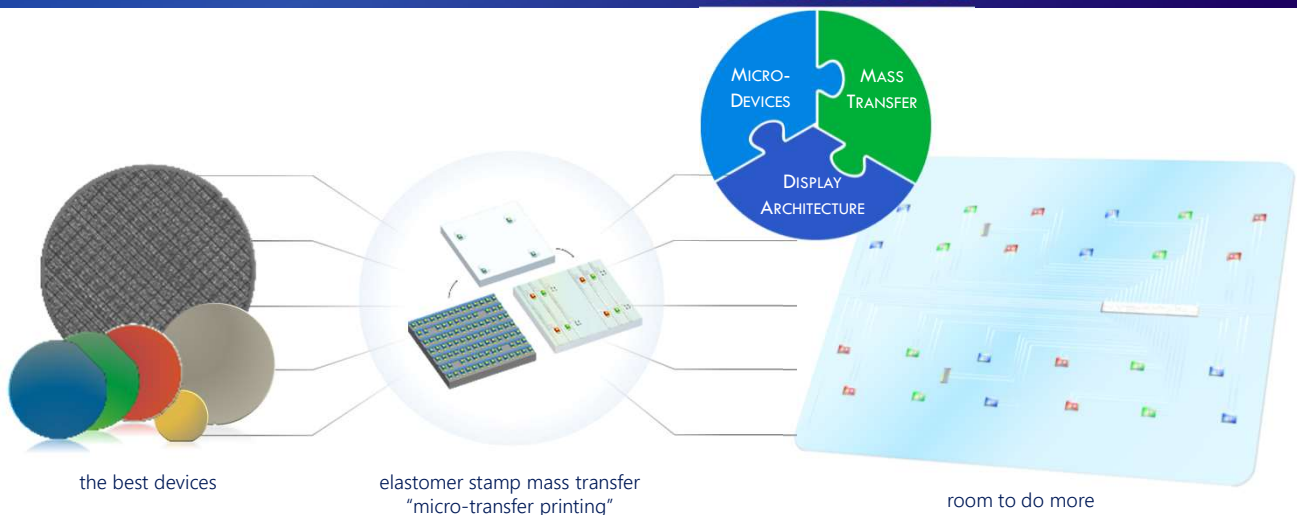


November 2008

63.2 AMOLED Displays using Transfer-Printed Integrated Circuits, *SID 2009*

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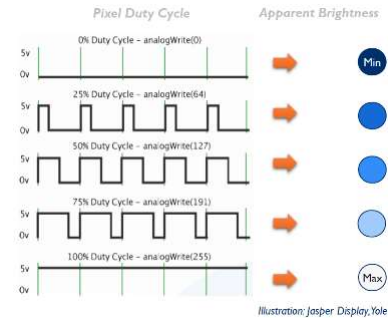
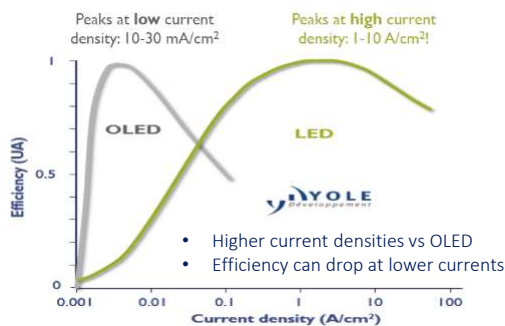
## microLED displays are a union of different disciplines.



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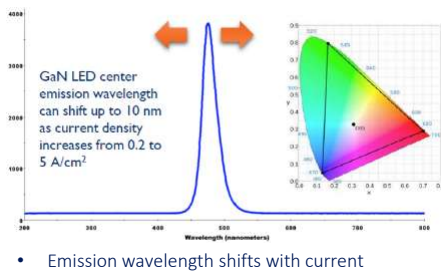
## Drive currents and microLEDs



- More complex digital PWM drive to maintain efficiency and color quality



- Mass transfer of microIC pixel drivers is a candidate solution



MicroLED Displays 2019 | www.yole.fr | ©2019

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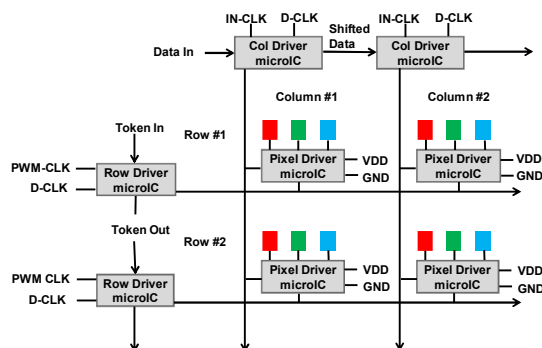
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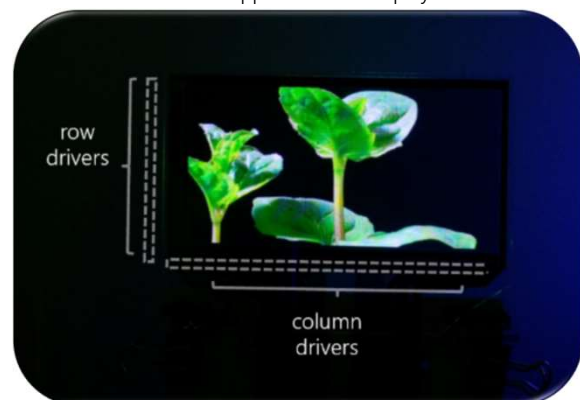
## The UltraMatrix™ digital display architecture

### An active-matrix PWM architecture using mass transferred microICs

- Column driver microICs demultiplex data
- Row driver microICs run progressive scan of data load and PWM
- Pixel driver microICs receive and store 48-bit digital data per frame
- Pixel driver microICs drive three subpixels using 14-bit PWM
- The subpixel current level is set using 2-bits



5.1" 70ppi microLED display



TOUCH TAIWAN and IMID 2018

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## 5.1" 70ppi UltraMatrix™ Display

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## Functional Yield of Sub-Pixels in 5.1" display

320 x 160 sub-pixel yield maps

Implementation of redundancy in microICs, microLEDs, row & column lines.

Remaining yield impactors:

- Forward voltage of LEDs
- Metallization defects (laser cut)
- Transfer (typ. < 3 sub-pixels)

RED, 0 dark subpixels  
100% yield

GREEN, 2 dark subpixels  
99.996% yield

BLUE, 1 dark subpixels  
99.998% yield

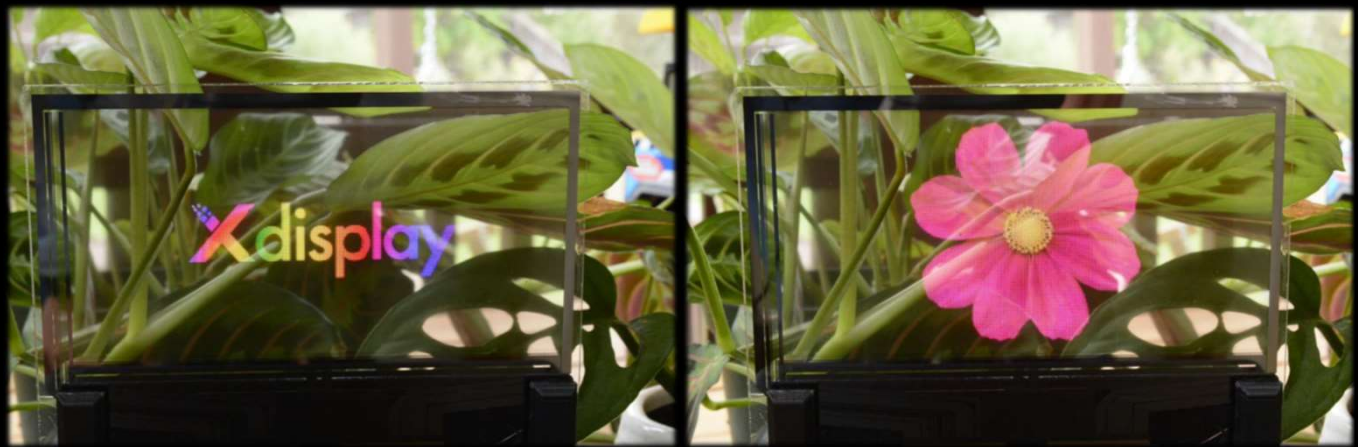
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## Transparent displays



320RGB x 160; 70PPI, fully redundant microIC and microLED architecture  
~ 73% transparency

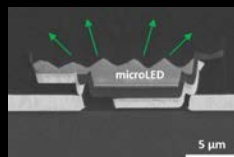
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## High brightness displays



30,000 nits (peak) green 5.1", 70ppi display outdoors



10,000 nits full color 5.1", 70ppi display behind paper veneer

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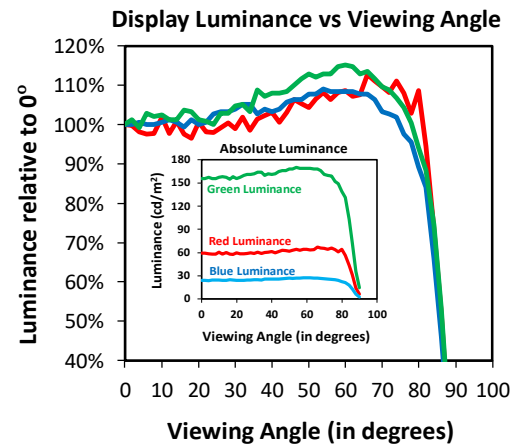
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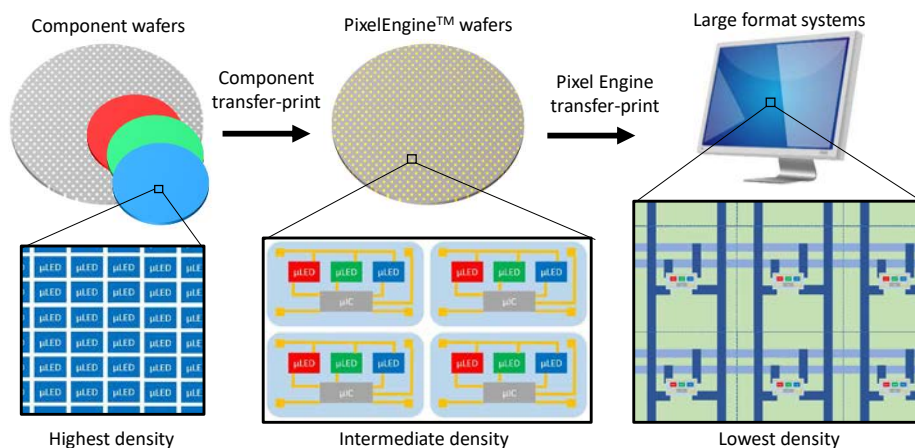
## Wide viewing angle from point-like emitters

5.1" 70ppi display with  $8 \times 15 \mu\text{m}^2$  microLEDs



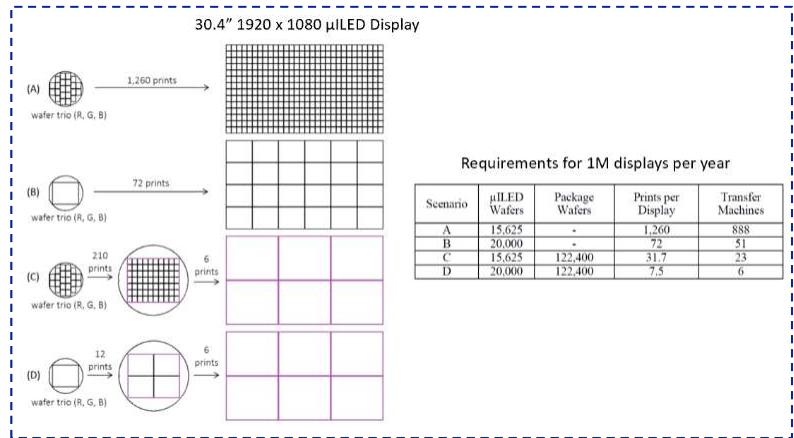
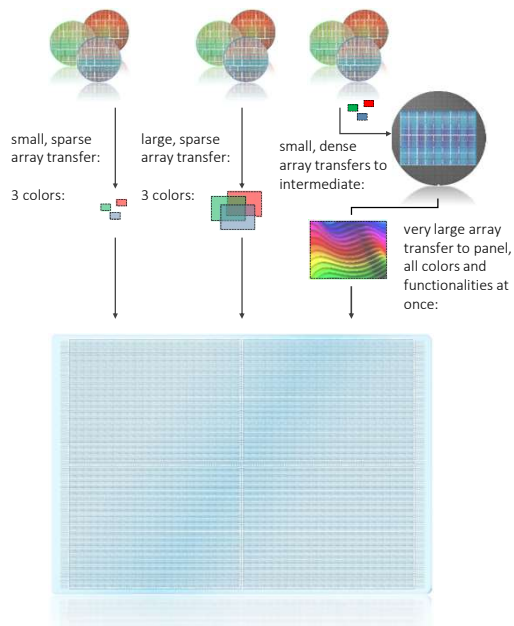
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## PixelEngine™ displays



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## Intermediate substrates can reduce transfer steps



Miniature Heterogeneous Fan-Out Packages for High-Performance, Large-Format Systems, Proc. ECTC, 2017

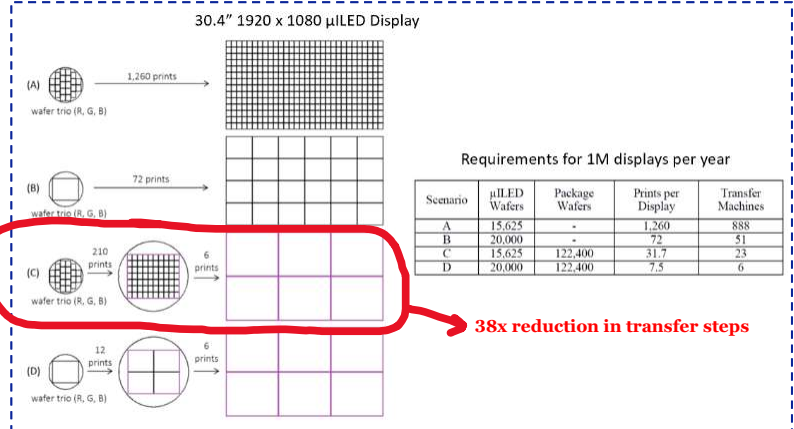
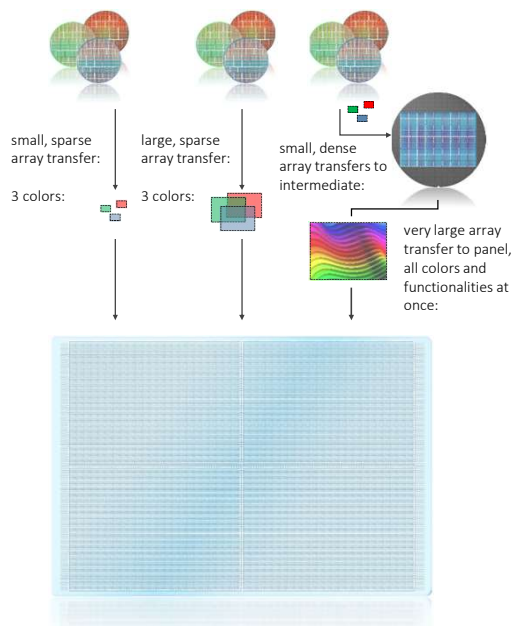
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## Intermediate substrates can reduce transfer steps



Miniature Heterogeneous Fan-Out Packages for High-Performance, Large-Format Systems, Proc. ECTC, 2017

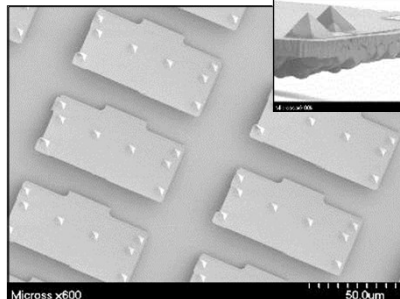
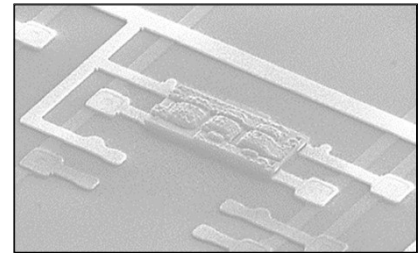
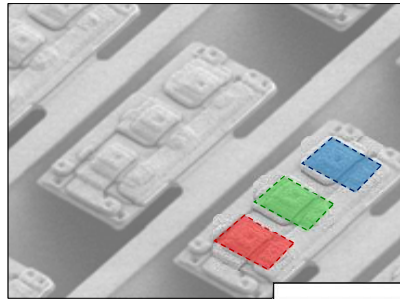
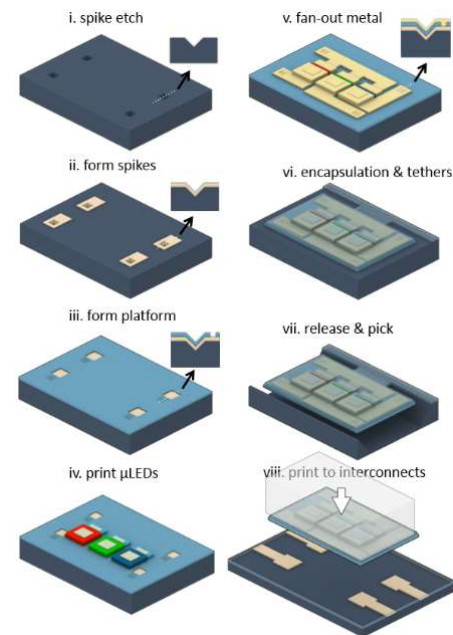
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## PixelEngine™ RGB package



Miniature Heterogeneous Fan-Out Packages for High-Performance, Large-Format Systems, Proc. ECTC, 2017

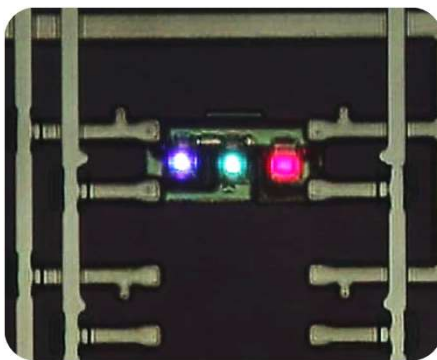
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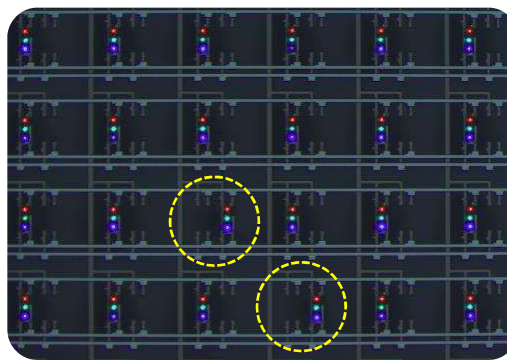
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## Demonstration of plug-in repair using connection "spikes"



Looking through substrate, see "divots" produced by spikes contacting metal at four corners of interposer.



Note repaired pixel on 2<sup>nd</sup> row from bottom, 3<sup>rd</sup> column from left: engine printed in redundant site by single-post stamp.



Simple passive matrix display prototype after additive repair.

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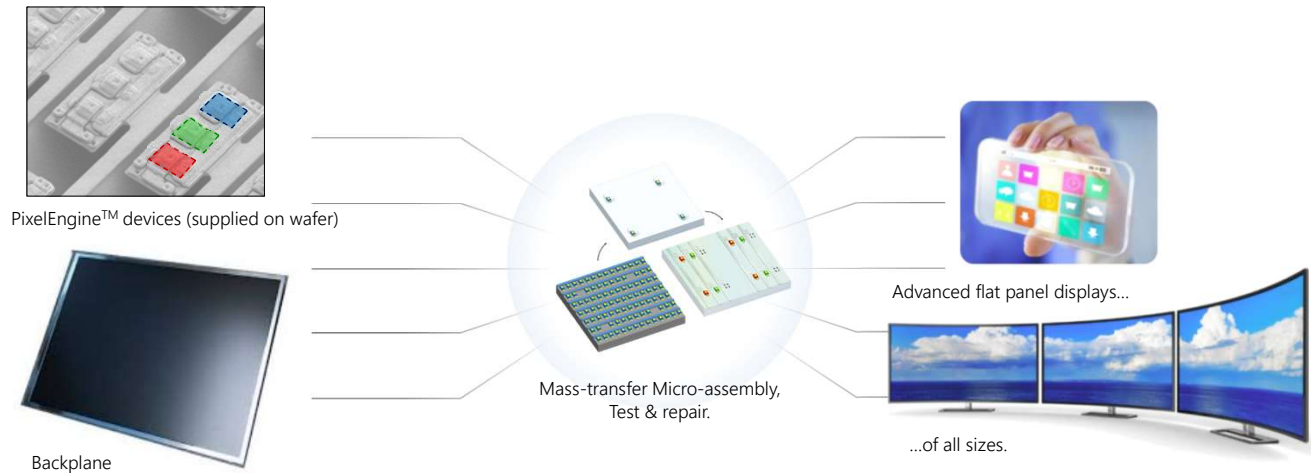
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## Assembly-centric display manufacturing

Additive assembly with electrical interconnection can finish displays at the “print, test & repair” process modules.



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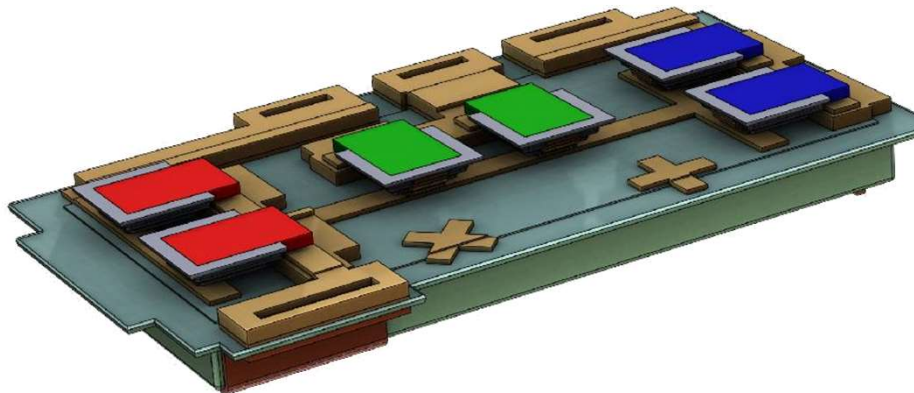
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## Combining microLEDs & microIC in a PixelEngine™ package

One micro transfer printable package that provides all active pixel components:

- pixel-level circuitry: pulse-width and/or –amplitude modulation.
- (redundant) set of flip-chip  $8 \times 15 \mu\text{m}^2$  microLEDs
- pressure concentrators for electrical contact



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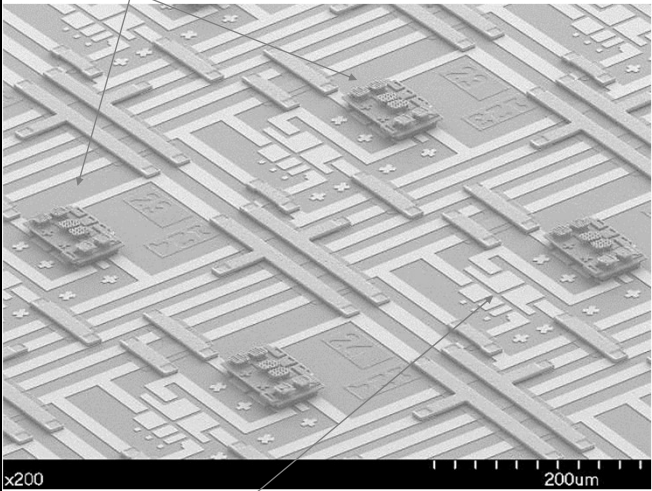
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## 70ppi PixelEngine™ display

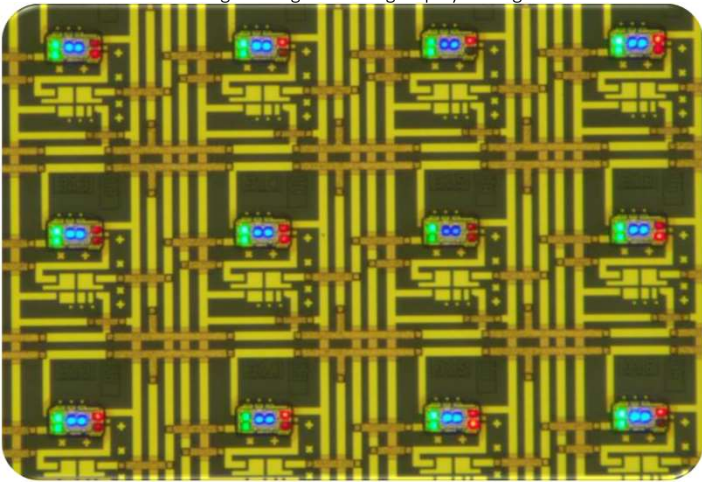

Engines transferred onto a backplane with two-wiring levels



x200 200um

Site for redundancy or repair

Energized engines during display testing





Sequence of colors from a redundant PixelEngine™ display

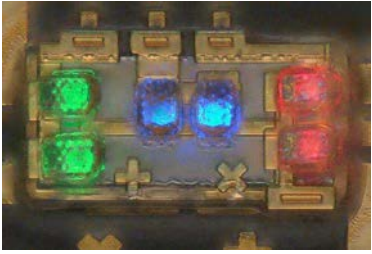

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## Thank you for watching!




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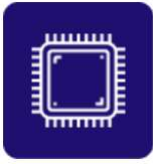
The PixelEngine™ company. Contact us at [info@xdisplay.com](mailto:info@xdisplay.com)

**Intellectual Property**




500+ patents

**Components**



microLEDs  
microICs  
PixelEngine™ devices

**Tools for R&D**



Mass transfer equipment  
Stamps

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